



SPN80N10A

N-Channel Enhancement Mode MOSFET

DESCRIPTION

The SPN80N10A is the N-Channel logic enhancement mode power field effect transistors are produced using high cell density, split gate DMOS trench technology. This high density process is especially tailored to minimize on-state resistance.

These devices are particularly suited for low voltage application, notebook computer power management and other battery powered circuits where high-side switching is required.

FEATURES

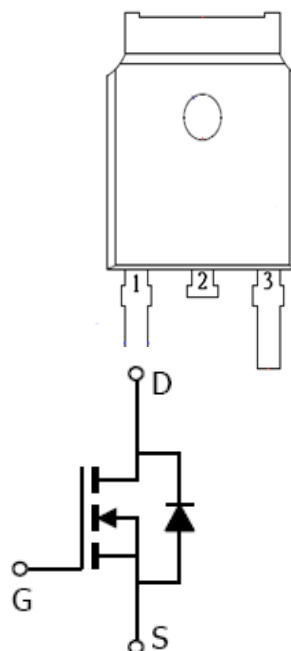
- ◆ 100V/74A, $R_{DS(ON)}=8.0\text{m}\Omega@V_{GS}=10\text{V}$
- ◆ 100V/74A, $R_{DS(ON)}=10.5\text{m}\Omega@V_{GS}=4.5\text{V}$
- ◆ Super high density cell design for extremely low $R_{DS(ON)}$
- ◆ Exceptional on-resistance and maximum DC current capability
- ◆ TO-252-2L package design

APPLICATIONS

- DC/DC Converter
- Load Switch
- Synchronous Buck Converter
- SMPS Secondary Side Synchronous Rectifier
- Power Tool
- Motor Control

PIN CONFIGURATION(TO-252-2L)

TO-252-2L



PART MARKING





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PIN DESCRIPTION

Pin	Symbol	Description
1	G	Gate
2	D	Drain
3	S	Source

ORDERING INFORMATION

Part Number	Package	Part Marking
SPN80N10AT220TGB	TO-220-3L	SPN80N10A
SPN80N10AT252RGB	TO-252-2L	SPN80N10A

※ SPN80N10AT252RGB : 13" Tape Reel ; Pb – Free ; Halogen – Free

※ SPN80N10AT220TGB : Tube; Pb – Free ; Halogen – Free

ABSOLUTE MAXIMUM RATINGS

(T_A=25°C Unless otherwise noted)

Parameter		Symbol	Typical	Unit
Drain-Source Voltage		V _{DSS}	100	V
Gate –Source Voltage		V _{GSS}	±20	V
Continuous Drain Current(Silicon Limited)	T _C =25°C	I _D	85	A
	T _C =100°C		54	
Pulsed Drain Current		I _{DM}	260	A
Avalanche Energy, Single Pulse (L=0.4mH , T _C =25°C)		E _{AS}	245	mJ
Power Dissipation, T _C =25°C	TO-220	P _D	104	W
	TO-252		93	
Operating Junction Temperature		T _J	-55/150	°C
Storage Temperature Range		T _{STG}	-55/150	°C
Thermal Resistance-Junction to Case	TO-252	R _{θJC}	1.35	°C/W

Note :

The maximum current rating is package limited at 70A for TO-252-2L



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ELECTRICAL CHARACTERISTICS

(T_A=25°C Unless otherwise noted)

Parameter	Symbol	Conditions	Min.	Typ	Max.	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{GS} =0V,I _D =250uA	100			V
Gate Threshold Voltage	V _{GS(th)}	V _{DS} =V _{GS} ,I _D =250uA	1.4	1.7	2.4	
Gate Leakage Current	I _{GSS}	V _{DS} =0V,V _{GS} =±20V			±100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} =80V,V _{GS} =0V T _J =25°C			1	uA
		V _{DS} =80V,V _{GS} =0V T _J =100°C			100	
Drain-Source On-Resistance	R _{DS(on)}	V _{GS} =10V,I _D =20A		6.5	8	mΩ
		V _{GS} =4.5V,I _D =10A		8.8	10.5	
Forward Transconductance	g _{fs}	V _{DS} =5V,I _D =10A		60		S
Gate Resistance	R _G	V _{GS} =0V,V _{DS} =Open, f=1MHz		1.3		Ω
Dynamic						
Total Gate Charge	Q _g (10V)	V _{DS} =50V,V _{GS} =10V I _D =20A		32		nC
Total Gate Charge	Q _g (4.5V)			16		
Gate-Source Charge	Q _{gs}			6		
Gate-Drain Charge	Q _{gd}			4		
Input Capacitance	C _{iss}	V _{DS} =50V,V _{GS} =0V f=1MHz		1876		pF
Output Capacitance	C _{oss}			348		
Reverse Transfer Capacitance	C _{rss}			5.6		
Turn-On Time	t _{d(on)}	V _{DD} =50V, I _D =20A,V _{GS} =10V R _G =10Ω		7		nS
	t _r			4		
Turn-Off Time	t _{d(off)}			20		
	t _f			3		
Reverse Recovery						
Diode Forward Voltage	V _{SD}	I _F =20A,V _{GS} =0V		0.9	1.2	V
Reverse Recovery Time	T _{rr}	V _R =50,I _F =20A, dI _F /dt=500A/uS		40		nS
Reverse Recovery Charge	Q _{rr}			161		nC



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TYPICAL CHARACTERISTICS

Fig 1. Typical Output Characteristics

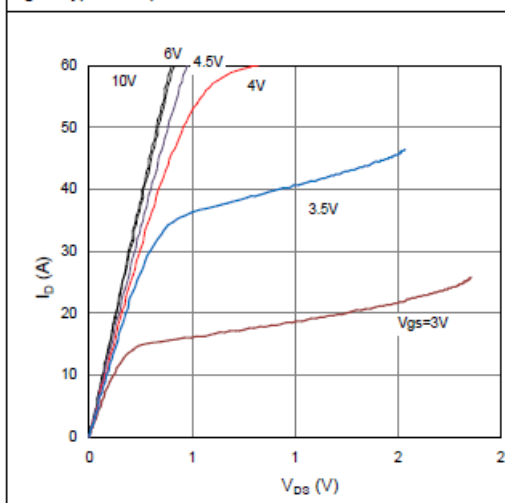


Figure 2. On-Resistance vs. Gate-Source Voltage

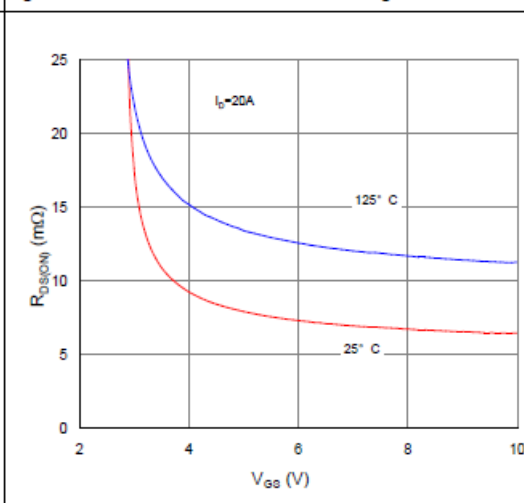


Figure 3. On-Resistance vs. Drain Current and Gate Voltage

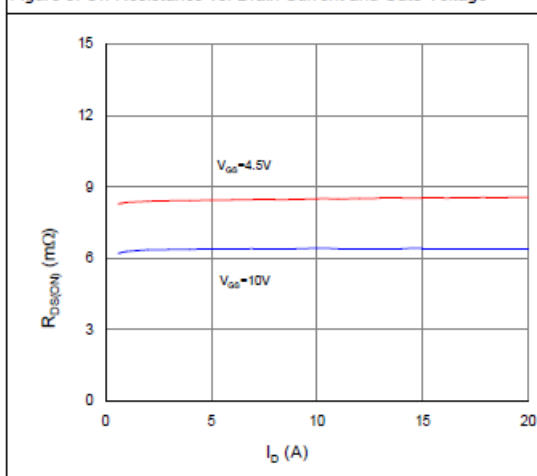


Figure 4. Normalized On-Resistance vs. Junction Temperature

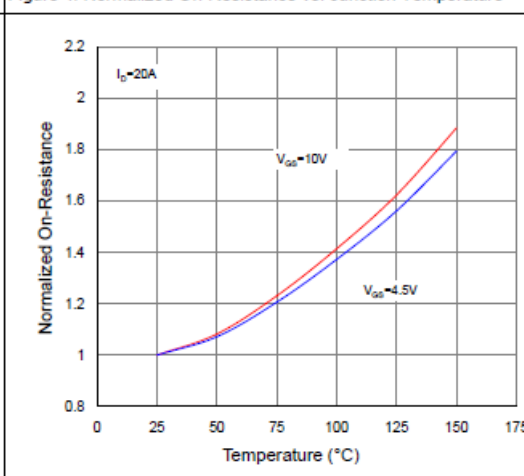


Figure 5. Typical Transfer Characteristics

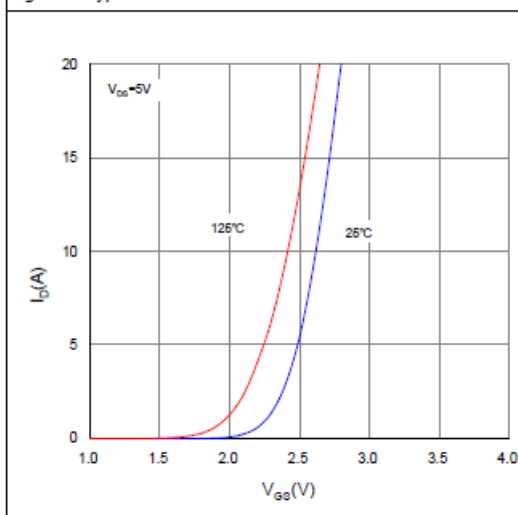
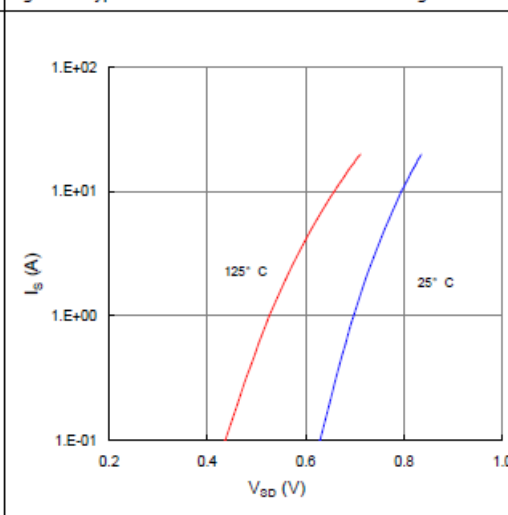


Figure 6. Typical Source-Drain Diode Forward Voltage





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TYPICAL CHARACTERISTICS

Figure 7. Typical Gate-Charge vs. Gate-to-Source Voltage

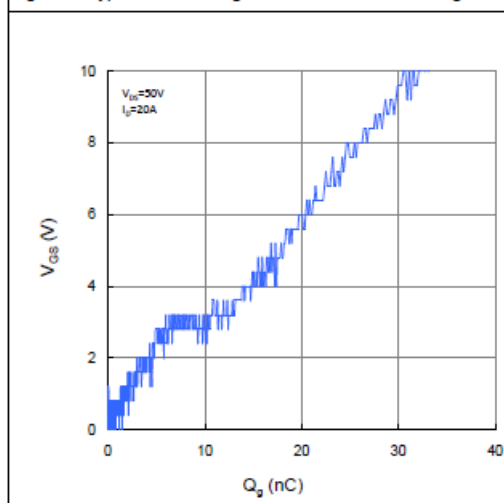


Figure 8. Typical Capacitance vs. Drain-to-Source Voltage

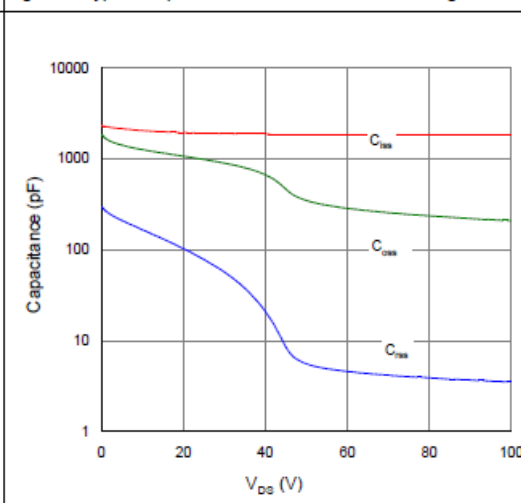


Figure 9. Maximum Safe Operating Area

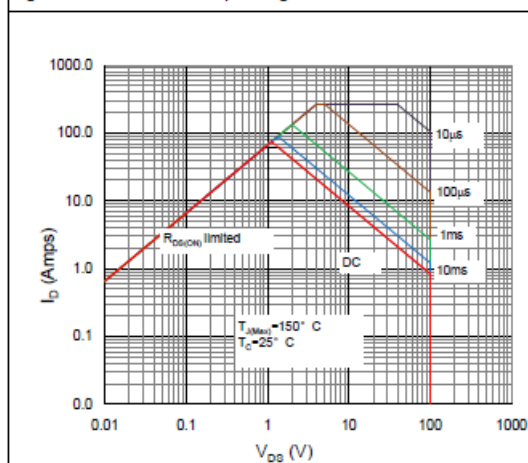


Figure 10. Maximum Drain Current vs. Case Temperature

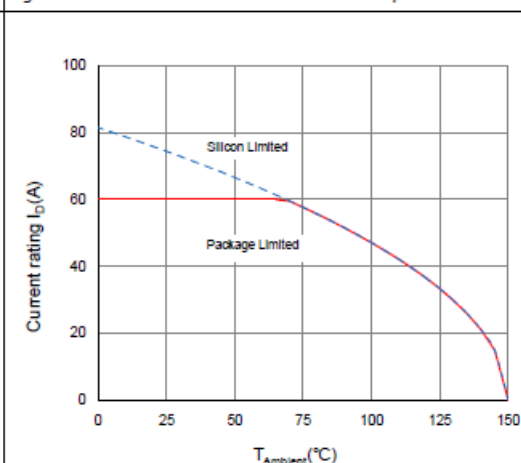
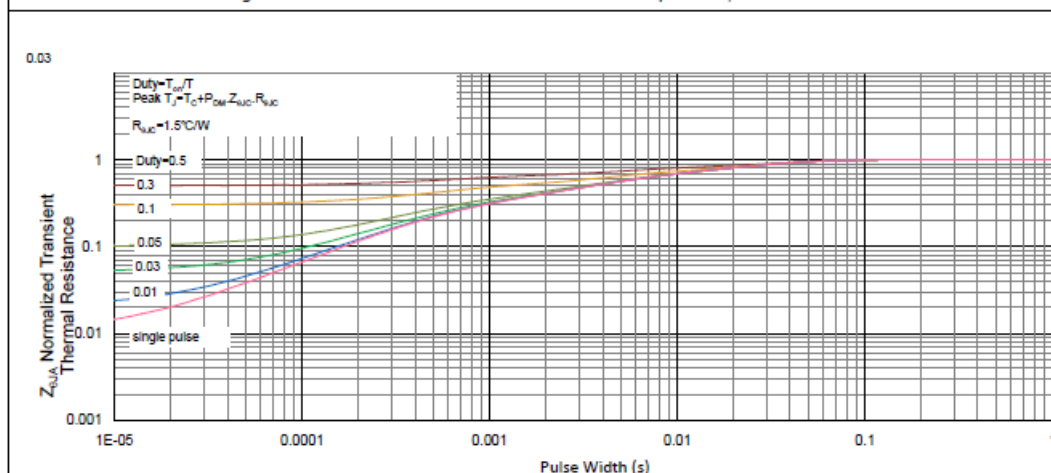


Figure 11. Normalized Maximum Transient Thermal Impedance, Junction-to-Ambient





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